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(54) Title: A METHOD FOR FABRICATING SEMICONDUCTOR ARTICLES AND SYSTEM THEREOF

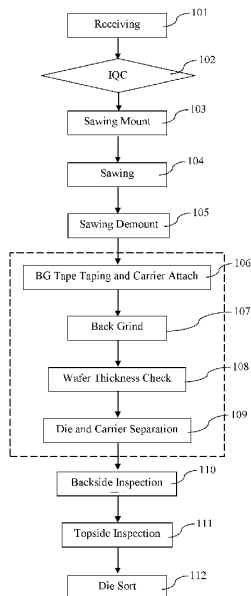


FIG. 1

(57) Abstract: The present invention discloses a method for fabricating semiconductor articles comprising the steps of partially cutting a wafer, applying one or more layers of adhesive sheet onto a carrier, transferring the partially cut wafer onto the adhesive sheet on the carrier; grinding a backside of the wafer to a desired thickness to form separated dies, and removing the separated dies from the carrier, wherein the separated dies are removed from the carrier by adhering another layer of adhesive sheet to the backside of the separated dies, in which a heated plate is pressed onto said adhesive sheet thereafter.

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